

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

2CL70A-MS/2CL71A-MS

Product specification

Features

- Super small size
- High reliability
- High speed switching

Typical Applications

Rectification for high voltage power supply of color T.V、CRT display、V.T.R camera and others

Mechanical Data


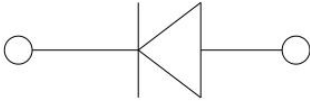


Package: DO-206

Epoxy meets UL 94 V-0 flammability rating

Terminals: Pure tin plated leads, solderable per J-STD-002 and JESD22-B102

Polarity: Color band denotes the cathode end

Reference News

PACKAGE OUTLINE	Pin Configuration	Marking	
			
		2CL70A-MS	2CL71A-MS

Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	2CL70A-MS	2CL71A-MS
Device marking code				T70A	71A
Repetitive Peak Reverse Voltage	V_{RRM}	KV		6	8
Non-Repetitive Peak Reverse Voltage	V_{RSM}	KV		8	10
Average Forward Current	$I_{F(AV)}$	mA	60Hz half-sine wave, Resistance load, Ta=25°C	5	
Non-Repetitive Forward Surge Current	I_{FSM}	A	60Hz half-sine wave, 1 cycle, Ta = 25°C	0.5	
Peak Forward Voltage	V_{FM}	V	$I_{FM}=10mA$	24	30
Peak Reverse Current	I_{RRM}	μA	$V_{RM}=V_{RRM}$, Ta=25°C	2	
			$V_{RM}=V_{RRM}$, Ta=100°C	5	
Reverse Recovery time	t_{rr}	μs	$I_F=2mA, I_{RM}=4mA, I_{RR}=1mA$	0.08	
Operating Ambient Temperature	T_a	°C		-40 ~ +100	
Storage Temperature	T_{stg}	°C		-40 ~ +120	
Virtual Junction Temperature	$T_{(vj)}$	°C		120	

Characteristics (Typical)

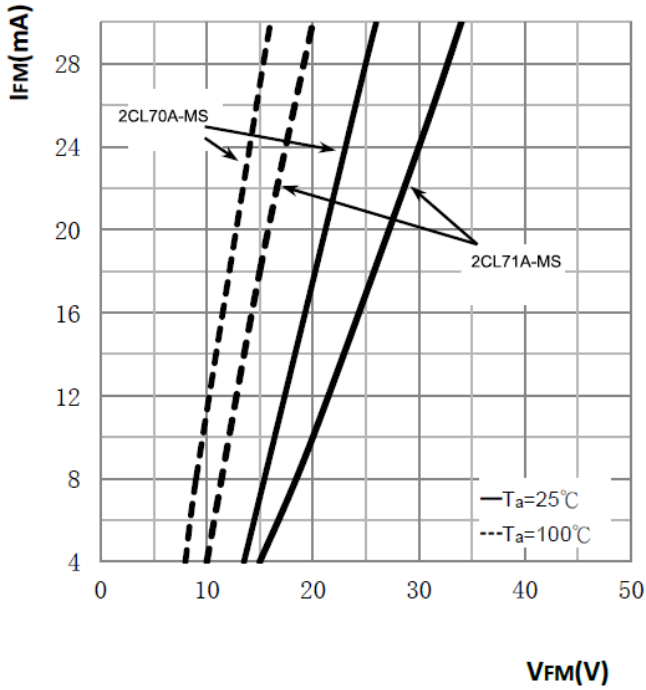


Figure 1. Forward characteristics

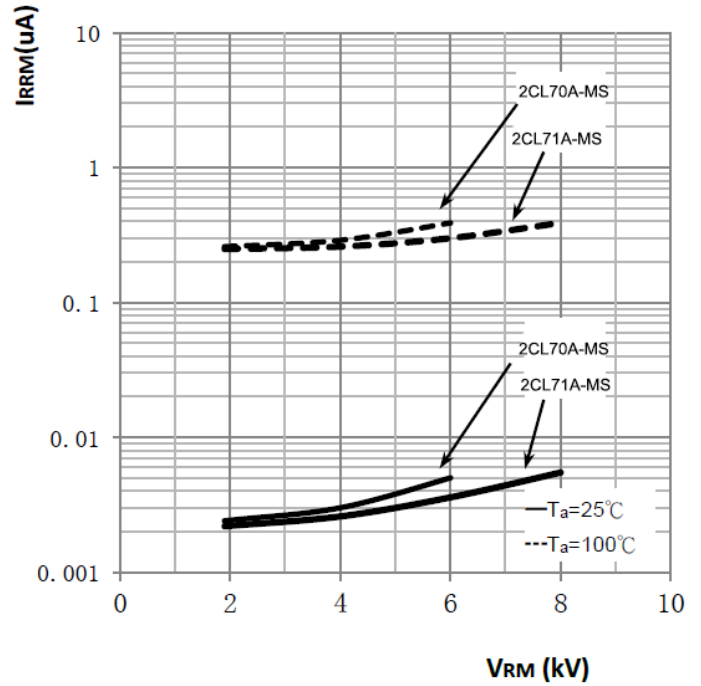


Figure 2. Reverse characteristics

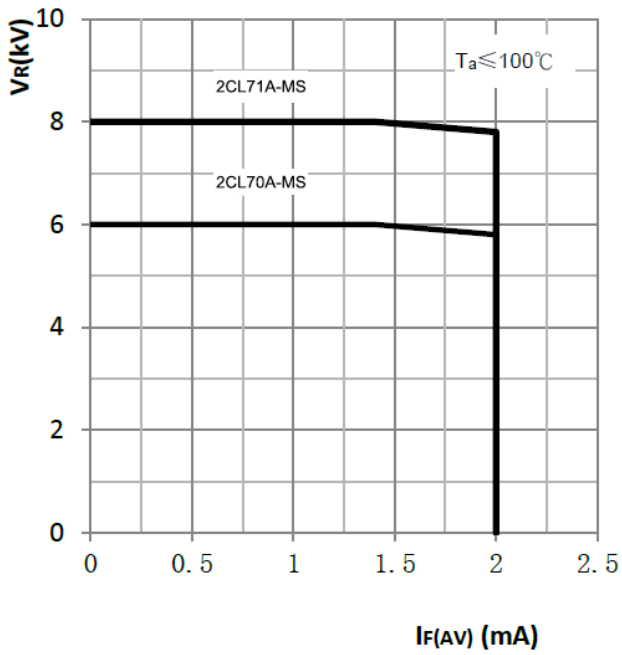


Figure 3. V_R - $I_{F(AV)}$ Curve

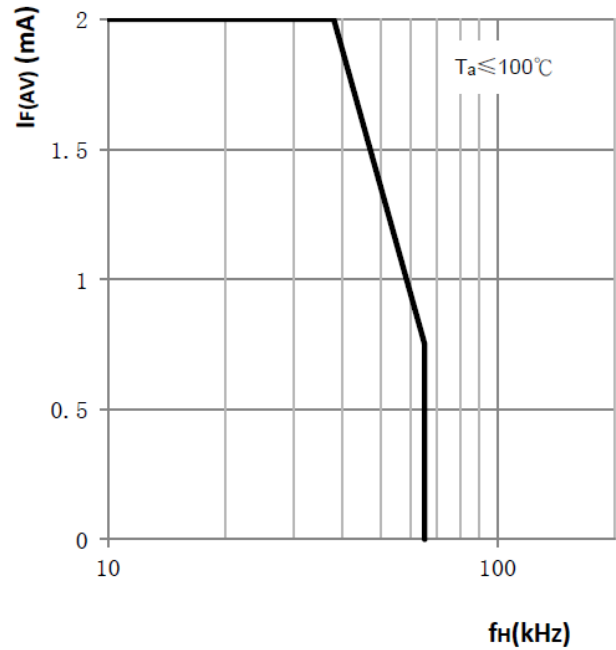
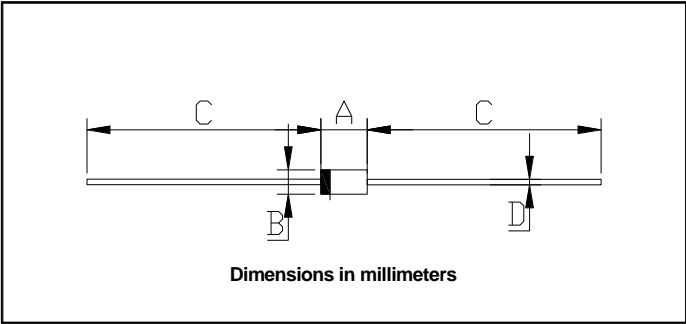


Figure 4. $I_{F(AV)}$ - f_H Curve

Outline Dimensions



DO-206		
Dim	Min	Max
A	6.3	6.7
B	2.3	2.7
C	26	/
D	0.47	0.53

Order information

Orderable Device	Package	Packing Option
2CL70A-MS/2CL71A-MS	DO-206	5000PCS

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